

On page 11, lines 10-13,

(Amended) According to the present invention, even if an open defect is detected in an electrode, the defect can be repaired by a metallic thin film of high quality that has good electric characteristics that avoids the need to heat the substrate, which can damage a substrate.

On page 11, lines 14-19,

(Amended) Further, according to the present invention, only the paste placed in the defect is heated and other portions of the substrate are not heated by the semiconductor laser used to bake the paste, and hence the substrate does not suffer damage. Furthermore, the metal in the defect is treated by a baking process comprising provisional baking and main baking process and a cooling process, and hence a dense metallic thin film with no cracks can be produced.

In the Claims:

Please rewrite claims 5-8 as follows:

5. (Amended) A method for repairing a metallic pattern on a substrate, said method comprising steps of:

applying a metallic organic compound to a defect in a metallic pattern overlying said substrate; and

subjecting said organic compound to a provisional baking process using a laser and a main baking process to deposit a metallic thin film in said defect.

6. (Amended) A method for repairing a metallic pattern on a substrate according to claim 5, wherein energy from a semiconductor laser is used as a heat source for baking said metallic organic compound.